MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

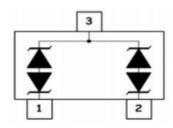
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Semiconductor Compiance

PIN CONFIGURATION





S0T-23

FEATURES

♦IEC61000-4-2 (ESD) ±30kV (Contact) ±30kV (Air)

- ♦IEC61000-4-4 (EFT) 40A (5/50ns)
- ♦350 Watts Peak Pulse Power per (tp=8/20µs)
- ♦Protects two bidirectional lines
- **♦Low clamping voltage**
- ♦ Working voltages: 3.3V to 36V
- **♦Low leakage current**

MACHANICAL DATA

- ♦SOT-23 package
- **♦Flammability Rating: UL 94V-0**
- ♦Packaging: Tape and Reel
- ♦High temperature soldering guaranteed: 260C/10s
- ♦Reel size: 7 inch
- ♦MSL 1

APPLICATIONS

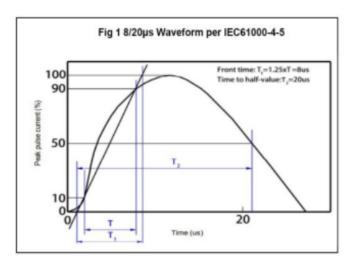
- *♦ Cell Phone Handsets and Accessories </u>*
- **♦**Microprocessor based equipment
- ♦Personal Digital Assistants (PDA's)
- ♦Notebooks, Desktops, and Servers
- **♦Portable Instrumentation**
- Networking and Telecom
- **♦Serial and Parallel Ports.**

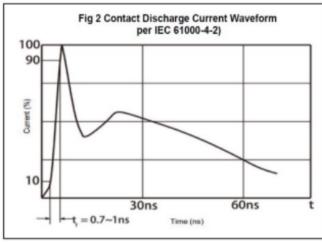
BSOLUTE MAXIMUM RATING					
Symbol	Parameter Value				
M	ESD per IEC 61000-4-2 (Contact)	±30	147		
V _{ESD}	ESD per IEC 61000-4-2 (Air)	±30	kV		
P _{PP}	Peak Pulse Power (8/20µs) 350				
Торт	Operating Temperature	-55/+150	°C		
T _{STG}	Storage Temperature	-55/+150			
T∟	Lead Soldering Temperature	260 (10 sec.)	°C		



ELECTRICAL CHARACTERISTICS (Tamb=25 ⁰ C)									
P/N	MARK	V _{RWM} (V) (max.)	V _B (V) (min.)	I⊤ (mA)	V _○ @1A (V) (max.)	(max.)	/c /) (@A)	I _R (μA) (max.)	C _J (pF) (max.)
SDT23C05L02-MS	C05	5. 0	6. 0	1	9. 8	18. 0	17	10	200
SDT23C12L02-MS	C12	12. 0	13. 3	1	19. 0	32. 0	11	1	75
SDT23C15L02-MS	C15	15. 0	16. 7	1	24. 0	38. 0	10	1	68
SDT23C24L02-MS	C24	24. 0	26. 7	1	43. 0	52. 0	7	1	50

ELECTRICAL CHARACTERISTICS CURVE



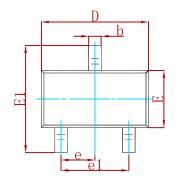


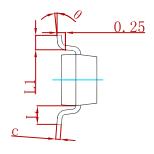


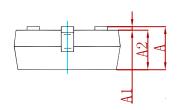




PACKAGE MECHANICAL DATA

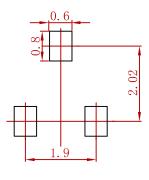






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950) TYP	0.037	7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SDT23CXXL02-MS	SOT-23	3000



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